



THE HONG KONG POLYTECHNIC UNIVERSITY
HONG KONG COMMUNITY COLLEGE
香港理工大學香港專上學院

This is to certify that

LAM Yik Shing

having satisfied the examiners
and having fulfilled all other requirements
has been awarded the

ASSOCIATE IN ENGINEERING

with Distinction

30 September 2018

二零一八年九月三十日

此證

成績優異

工程學副學士

考試及格照章頒授

林奕成

修業期滿

University President

College Director



香港專上學院院長 梁德榮



香港理工大學校長 唐偉章





TRANSCRIPT OF STUDIES
學業成績表

Name (in English) LAM Yik Shing
HKID No. Y5906**(*)
Year of Award 2018
Award Associate in Engineering
(with Distinction)

Name (in Chinese) 林奕成
Student No. 16173359A
Date of Issue 30 Sep 2018

Programme: Associate in Engineering		Mode of Study: Full-Time	
Attendance: 2016/17 Semester 1 to 2017/18 Semester 2			
Subject Code	Subject Title	Credit	Grade/Code
2016/17 Semester 1 GPA (cumulative): 3.90			
CCN1003	Chinese Communication for College Students	3.0	B+
CCN1004	Creative and Critical Thinking	3.0	A
CCN1045	Calculus	3.0	A+
CCN1046	English for Academic Studies (Science and Technology) I	3.0	B
CCN2041	Applied Computing	3.0	A+
2016/17 Semester 2 GPA (cumulative): 3.90			
CCN1047	English for Academic Studies (Science and Technology) II	3.0	B
CCN1048	Introduction to Linear Algebra	3.0	B+
CCN1049	Physics I	3.0	A+
CCN1050	Introduction to Probability and Statistics	3.0	A+
CCN1051	Physics II	3.0	A
2017/18 Semester 1 GPA (cumulative): 3.88			
CCN2004	Managing Organisations	3.0	A
CCN2042	Computer Programming	3.0	A+
CCN2246	Basic Electricity and Electronics	3.0	B+
CCN2250	Engineering Mathematics	3.0	B
CCN2262	Architectural Technology in the Built Environment	3.0	A+
CCN2269	Engineering Graphics and Computing	3.0	B+



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Name (in English) LAM Yik Shing
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Date of Issue 30 Sep 2018

2017/18 Semester 2 GPA (cumulative): 3.69

CCN1024	Putonghua for College Students
CCN2249	Engineering Materials
CCN2272	Logic Design
CCN2281	Introduction to Classical Chinese Poetry
CCN3134	Engineering Economics

3.0	B
3.0	A
3.0	C+
3.0	C+
3.0	B+

***** Transcript Total *****

Total Credits Required : 63.0

Total Credits Attained : 63.0

GPA : 3.69 Award GPA : 3.69

***** End of Transcript *****



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